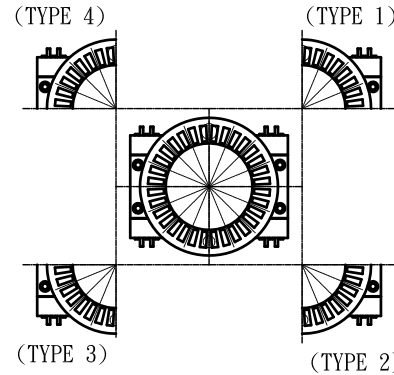
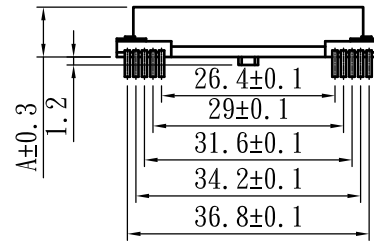
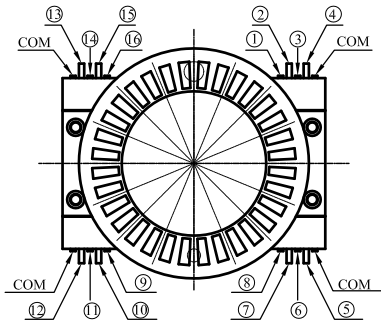


LED-CCL-A-□-□□□□-6H

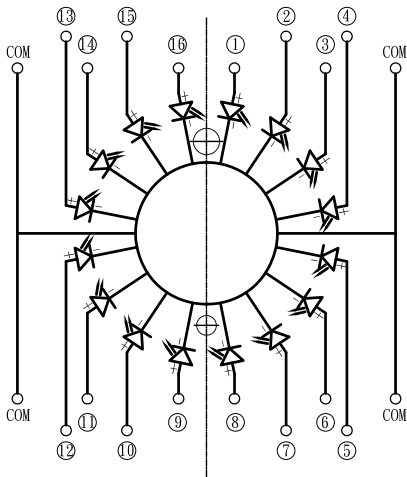
Type 1~4:

Code	Color of LED
R	Red Orange
Y	Yellow
G	Pure Green
B	Blue

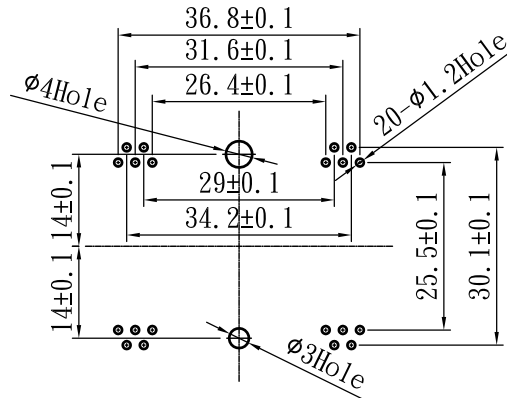


A
7.6mm
3.1mm

LED Color type



CIRCUIT DIAGRAM



P.C.B mounting hole dimensions

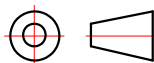
ROHS COMPLIANCE

NOTES:

TOLERANCES	
less than 6	±0.2
6 - 18	±0.25
18 - 50	±0.3
50 - 125	±0.4
Angular dimension	±1°

CODE NO.					MODEL NAME:	LED-CCL-A-□-□□□□-6H			
PATH:	LED-CCL/Part				DRAWING NO.				
MATERIAL	APPROVED SIGNATURES	DRAWN BY	CHECKED BY	APPROVED BY	UNIT	m/m	SCALE	1 / 1	
FINISHING		鐘學峰	余倩	鐘學峰					
TOLERANCES									
VERSION	A	2009.4.27	2009.4.27	2009.4.27					

Third Angle Projection



可正欣部品圖框
TOP-UP INDUSTRY CORP.

2009.4.27 Zhong xue feng 首次出圖

LED-CCL SPECIFICATIONS

◆ SUPER PURE GREEN (AlGaInP/GaAs)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	pure green
Power dissipation per dice	P _{AD}	70
Continuous forward current per dice	I _{AF}	25
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	90
Reverse voltage per dice	V _R	5
Operating temperature	T _{OPR}	-40°C to +105°C
Storage temperature	T _{STG}	-40°C to +105°C

ELECTRICAL – OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Type	Max.	Unit	
Forward Voltage	V _F	I _F =20mA	2.8	3.2	3.6	V	
Reverse Current	I _R	V _R =5V	-	-	1	μA	
Peak Wavelength	λ _P	I _F =20mA	-	517	-	nm	
Dominant Wavelength	λ _d	I _F =20mA	500	-	535	nm	
Luminous Intensity	Per segment	I _V	I _F =20mA	160	-	350	mcd
	Per Decimal Point			-	-	-	
Spectrum Radiation Bandwidth	Δλ	I _F =20mA	-	30	-	nm	

◆ SUPER BRIGHT YELLOW (AlGaInP/GaAs)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Super Bright Yellow
Power dissipation per dice	P _{AD}	70
Continuous forward current per dice	I _{AF}	25
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	90
Reverse voltage per dice	V _R	5
Operating temperature	T _{OPR}	-40°C to +105°C
Storage temperature	T _{STG}	-40°C to +105°C

ELECTRICAL – OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Type	Max.	Unit	
Forward Voltage	V _F	I _F =20mA	-	2.05	2.4	V	
Reverse Current	I _R	V _R =5V	-	-	10	μA	
Peak Wavelength	λ _P	I _F =20mA	-	587	-	nm	
Dominant Wavelength	λ _d	I _F =20mA	581	585	589	nm	
Luminous Intensity	Per segment	I _V	I _F =20mA	-	-	-	mcd
	Per Decimal Point			-	-	-	
Spectrum Radiation Bandwidth	Δλ	I _F =20mA	-	15	-	nm	

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LED-CCL SPECIFICATIONS

◆ SUPER BRIGHT BLUE (InGaN)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Super Bright Blue
Power dissipation per dice	P _{AD}	120
Continuous forward current per dice	I _{AF}	30
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	100
Reverse voltage per dice	V _R	5
Operating temperature	T _{OPR}	-40°C to +105°C
Storage temperature	T _{STG}	-40°C to +105°C

ELECTRICAL – OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Type	Max.	Unit	
Forward Voltage	V _F	I _F =20mA	2.7	2.85	3.0	V	
Reverse Current	I _R	V _R =5V	-	-	10	μA	
Peak Wavelength	λ _p	I _F =20mA	-	465	-	nm	
Dominant Wavelength	λ _d	I _F =20mA	450	465	480	nm	
Luminous Intensity	Per segment	I _V	I _F =20mA	10	30	40	mcd
	Per Decimal Point			-	-	-	
Spectrum Radiation Bandwidth	Δλ	I _F =20mA	-	30	-	nm	

◆ SUPER BRIGHT RED ORANGE (AlGaInP/GaAs)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Super Bright Red Orange
Power dissipation per dice	P _{AD}	70
Continuous forward current per dice	I _{AF}	25
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	90
Reverse voltage per dice	V _R	5
Operating temperature	T _{OPR}	-40°C to +105°C
Storage temperature	T _{STG}	-40°C to +105°C

ELECTRICAL – OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Type	Max.	Unit	
Forward Voltage	V _F	I _F =20mA	-	2.0	2.4	V	
Reverse Current	I _R	V _R =5V	-	-	10	μA	
Peak Wavelength	λ _p	I _F =20mA	-	632	-	nm	
Dominant Wavelength	λ _d	I _F =20mA	619	624	629	nm	
Luminous Intensity	Per segment	I _V	I _F =20mA	-	35	-	mcd
	Per Decimal Point			-	35	-	
Spectrum Radiation Bandwidth	Δλ	I _F =20mA	-	20	-	nm	

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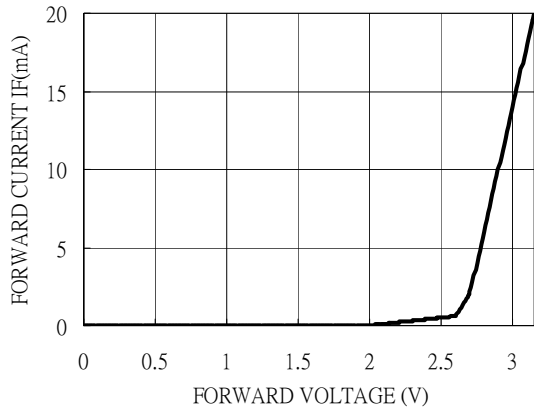
LED-CCL SPECIFICATIONS

◆ TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

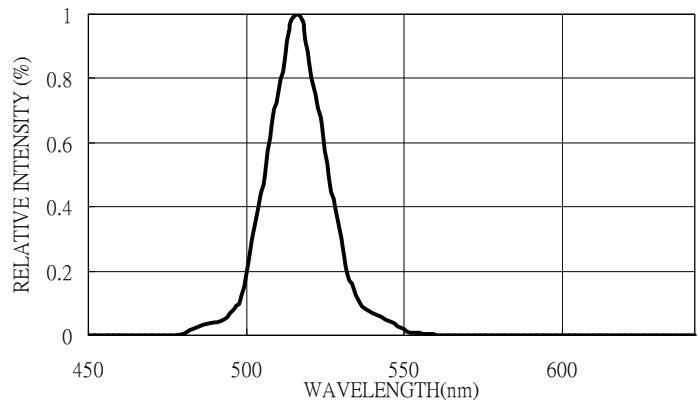
(25°C Free Air Temperature Unless Otherwise Specified)

Super Pure Green (AlGaInP/GaAs)

FORWARD CURRENT VS. FORWARD VOLTAGE

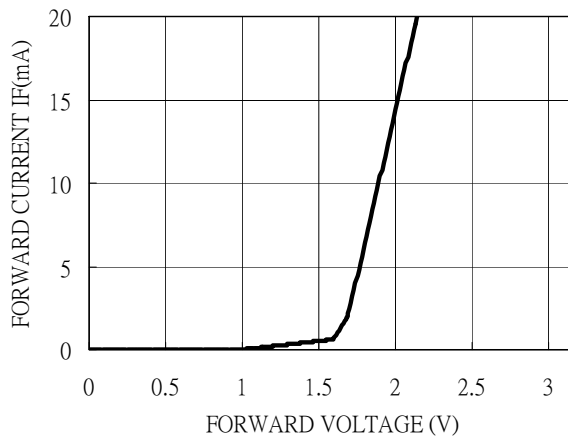


REALATIVE INTESITY VS. WAVELENGTH

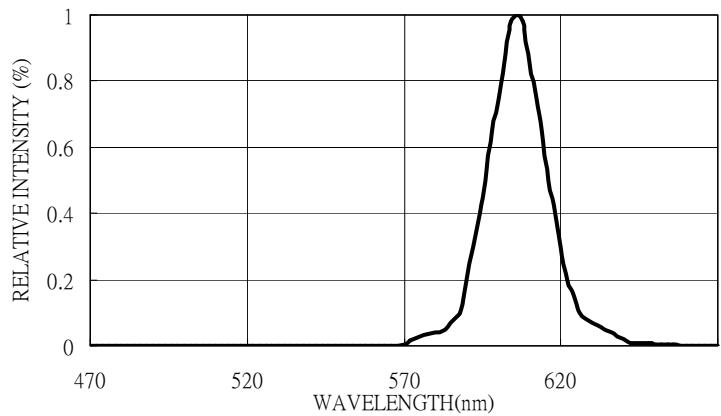


Super Bright Yellow (AlGaInP/GaAs)

FORWARD CURRENT VS. FORWARD VOLTAGE



REALATIVE INTESITY VS. WAVELENGTH



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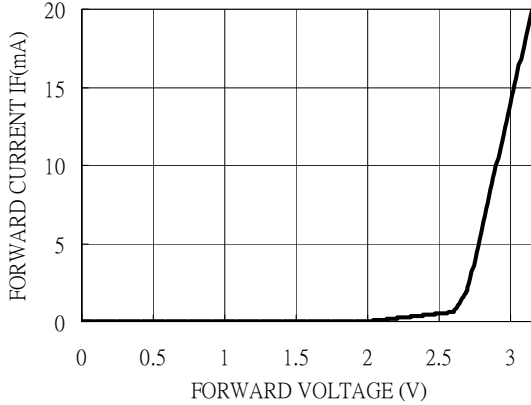
LED-CCL SPECIFICATIONS

◆ TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

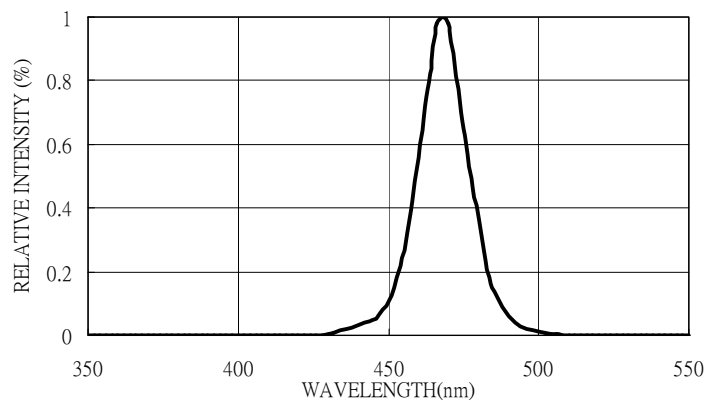
(25°C Free Air Temperature Unless Otherwise Specified)

Super Bright Blue (InGaN)

FORWARD CURRENT VS. FORWARD VOLTAGE

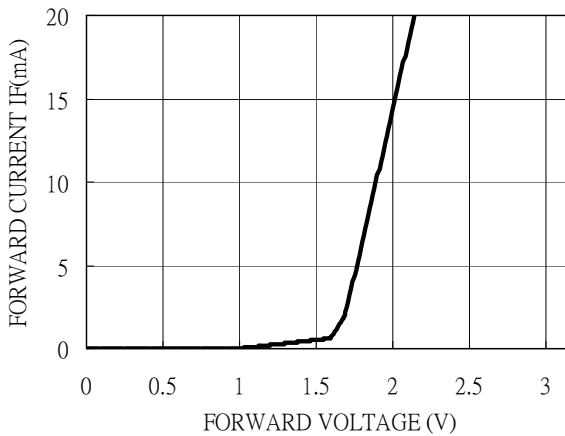


REALATIVE INTESITY VS. WAVELENGTH

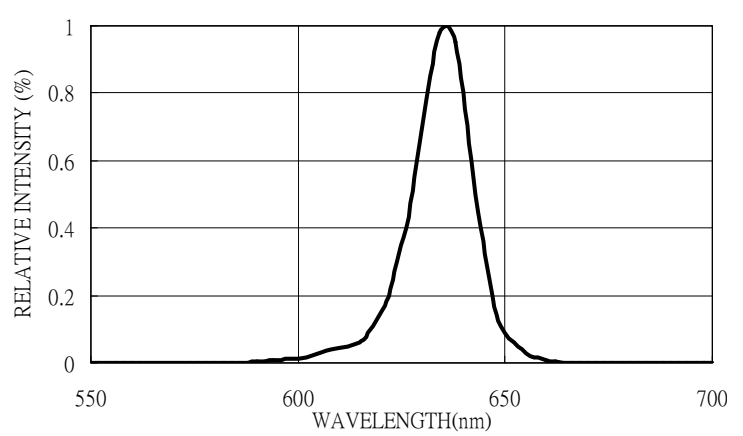


Super Bright RED ORANGE (AlGaInP/GaAs)

FORWARD CURRENT VS. FORWARD VOLTAGE



REALATIVE INTESITY VS. WAVELENGTH



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LED-CCL SPECIFICATIONS

◆ RELIABILITY SPECIFICATION

The Reliability of Products shall be satisfied with items listed below

NO	Item	Test Conditions	Test Hours/Cycle	Accept/Reject
1	Solder Heat	TEMP: 260°C±5°C	10 Sec	0/1
2	Temperature Cycle	-40°C~105°C (15min. ~5min.~15min.)	300 Cycles	0/1
3	Thermal Shock	-10°C~105°C (15min. ~10sec.~15min.)	300 Cycles	0/1
4	High Temperature Storage	TEMP:105°C	1000Hrs	0/1
5	Low Temperature Storage	TEMP:-40°C	1000Hrs	0/1
6	DC Operating Life	TEMP: 25°C I _F =20mA	1000Hrs	0/1
7	High Temperature/High Humidity	85°C/85% RH	1000Hrs	0/1

Note: Failure Judgment Criteria is $I_{v(\text{initial})} \leq I_{v(\text{final})} \times 0.5$ or $V_{f(\text{final})} \geq V_{f(\text{max})}$

$I_{v(\text{initial})}$: To test I_v value of the chip before the reliability test

$I_{v(\text{final})}$: The test value of the chip that has completed the reliability test

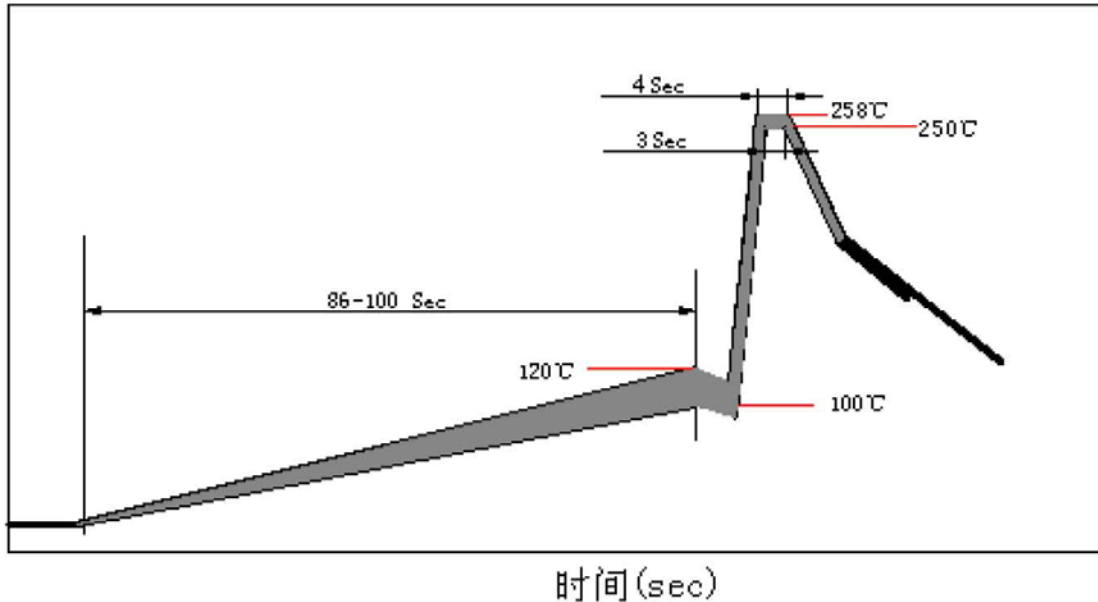
$V_{f(\text{final})}$: The test value of the chip that has completed the reliability test

$V_{f(\text{max})}$: Upper Specification Limit

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LED-CCL SPECIFICATIONS

◆ DIP soldering(Wave Soldering) :



Profile Feature	Dip Solder Assembly
Preheat Ramp-Up Rate	1~2°C/sec
Preheat Temperature Min	100°C
Preheat Temperature Min	120°C
Preheat Time	86~100sec
Peak/Classification Temperature	250~258°C
Time Within 5°C of Actual Peak Temperature	3~4sec
Ramp-Down Rate	1~3°C/sec
Time of All the Dip Solder Assembly	About 3.5 min

◆ Storage Condition

● 7.1.Storage Environment

-20 to 30°C, 20 to 60%RH.

(Storage in high temperature and high humidity shall be avoided).

● 7.2.After this bag is opened , devices that will be applied to infrared reflow , vapor-phase reflow ,or equivalent soldering process must be:

a).Completed within 24hours. b).Stored at less than 30%RH.

● 7.3.Devices require baking mounting ,if : 7.2 (a) or 7.2 (b) is not met.

● 7.4.If baking is required , devices must be baked under below conditions :

12hours at 60°C ± 3°C

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LED-CCL SPECIFICATIONS

1. Scope

This specification covers the requirements of the tray packaging for LED-CCL standard type of LED diaphragm.

2. Packaging Materials

Item	Material
Package	Cartons.
Tray	PET

3. Packaging Quantity

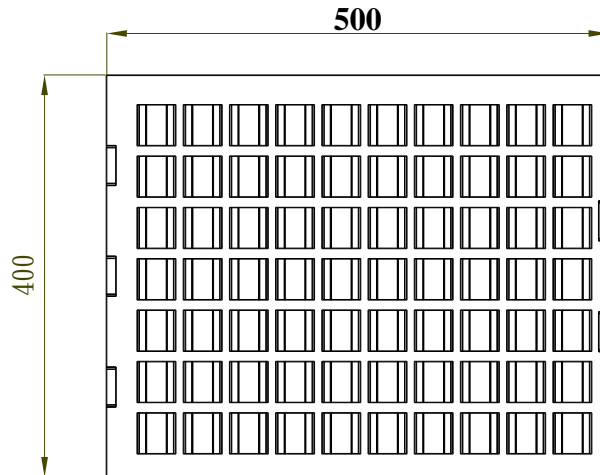
3.1. The number of the Package.

8 trays at maximum, which contain 560 LED diaphragms, shall be packed in a package.

3.2. The number of the LED diaphragms.

70 LED diaphragms shall be packed in a tray.

4. Tray Form and Dimensions



5. Storage Condition

5.1. Storage Environment

-20 to 30°C, 20 to 60%RH.

(Storage in high temperature and high humidity shall be avoided).

5.2. After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:

a). Completed within 24 hours. b). Stored at less than 30%RH.

5.3. Devices require baking mounting, if 7.2 (a) or 7.2 (b) is not met.

5.4. If baking is required, devices must be baked under below conditions:

12 hours at 60°C ± 3°C

ROHS COMPLIANCE

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